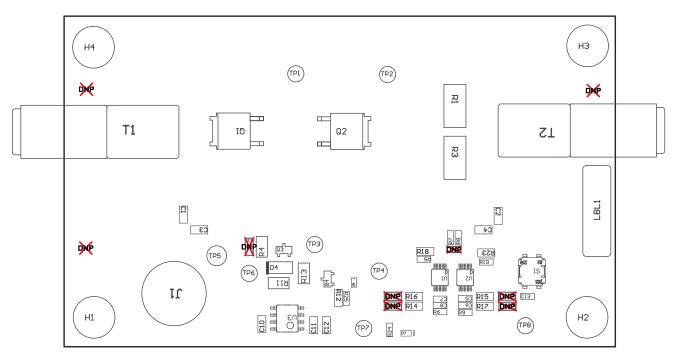
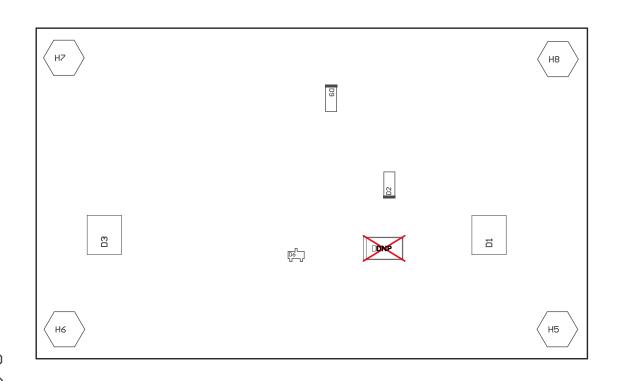
- ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00795	REV: E1	SVN REV: Not In VersionControl	
	TID #: TIDA-00795			
PLOT NAME = Top Assembly Drawing	GENERATED : 1/11/2	016 9:38:23	AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

	PCB VIEWED FROM BOTTOM	SIDE :# QAAC	IIT B	DA-00795 F	REV: E1	SUN REU: Not In VersionControl			
	TID #:TIDA-00795 TEXAS INSTRUMENTS								
Drawing	Bot ŧo⊡MA k/sē@DRy		GENERATED	: 1/11/2016	9:38:24 f	1 Μ			

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